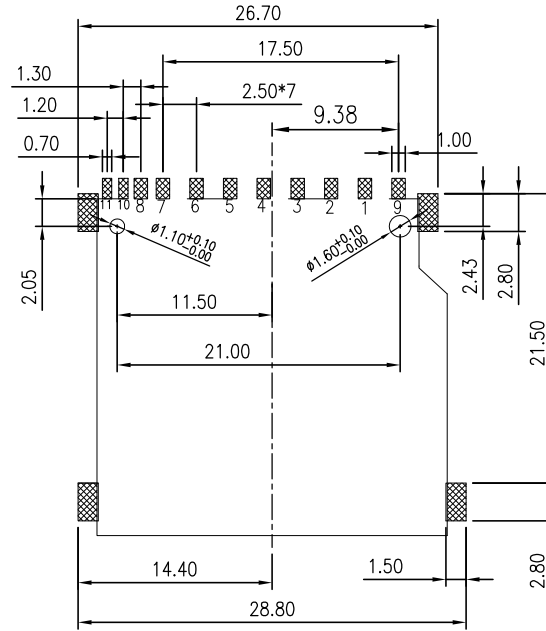
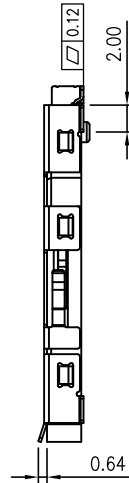
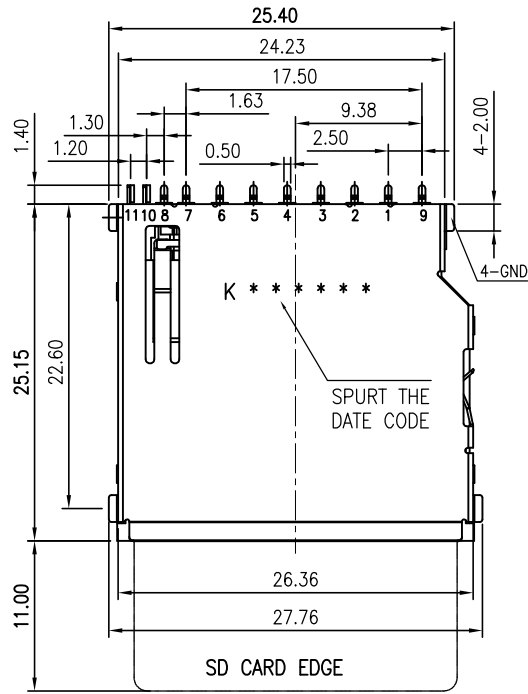


RoHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	2018.09.17	HFL		LHY
A1	ECN1810002	变更包装数量&增加D/C	2018.10.08	HFL		LHY

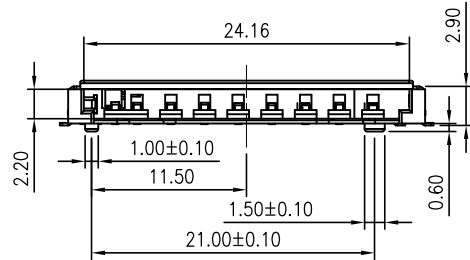


RECOMMENDED P.C.B LAYOUT
(TOLERANCE: +/-0.05)

NOTES:

- MATERIAL**
HOUSING : HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY
SHELL: COPPER ALLOY
- PLATING**
CONTACT AREA: 30u" PLATED OVER Ni
SOLDER TAIL: 100u" MIN Sn PLATED OVER Ni
SHELL SOLDER AREA: NICKEL PLATED
- RATING**
CURRENT RATING: 0.5A
VOLTAGE RATING: 250VRMS
OPERATING TEMPERATURE: -25°C~90°C
- SPECIFICATION**
CONTACT RESISTANCE: 100 M OHMS MAX
DIELECTIC WITHSTANDING VOLTAGE: 500VAC 1Min.
INSULATION RESISTANCE: 1000 MegOHMS MIN
INSERTION FORCE: 40 N MAX
SEPARATION FORCE: 1-10N
- DATE CODE 说明: K * * * * ***

星期: 01表示星期一
.....
07表示星期天
周: 01表示第一周
.....
12表示第十二周
年: 17表示2017年



SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	
11#	WP	

MILLIMETERS	INCH
X° ± 2'	X° ± 2'
.X ± 0.38	.XX ± 0.015
.XX ± 0.25	.XXX ± 0.010
.XXX ± 0.10	.XXXX ± 0.004

UNITS	MM
MAT'L	
SEE NOTES	
FINISH	
SEE NOTES	
QTY	
SEE NOTES	

XB 东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

PART NUMBER: XB-C- 102302652 TITLE: SD 长体 No Push

APPD: DWG NO.: C-102302652-00

CHKD: DR:

SCALE	SHEET	REV.
1:1	1/2	A1

